

Prof. Ching Ping WONG

BS (Purdue), Ph.D (Pennsylvania State), MNAE, FIEEE
Dean of Engineering, CUHK

Prof. C.P. Wong, a world-renowned scholar in electronic engineering, a member of the US National Academy of Engineering and an IEEE Fellow. He received his BS degree from Purdue University, and his PhD degree from Pennsylvania State University. After completing doctoral studies, he was awarded a postdoctoral fellowship under Nobel laureate Professor Henry Taube at Stanford University. He was also with AT&T Bell Laboratories for many years and became an AT&T Bell Laboratories Fellow in 1992. Prior to joining CUHK, he was the Regents' Professor of Georgia Institute of Technology, and Professor of Material Science and Engineering in Charles Smithgall Institute.



Widely recognized as an academic giant, Professor Wong's research interests lie in the fields of polymeric electronic materials, electronic, photonic and MEMS packaging and interconnect, interfacial adhesions, and nano-functional material syntheses and characterizations. He is considered an industry legend and has made significant contributions to the industry by pioneering new materials, which fundamentally changed semiconductor packaging technology. With excellent achievements in both teaching and research, Professor Wong has successfully motivated and nurtured numerous inquisitive young minds over the years. He is also committed to serving the industry by being the President of the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society in 1992 and 1993. As a distinguished scholar, Professor Wong was awarded numerous international honours, such as the IEEE CPMT Field Award and David Feldman Outstanding Contributions Award, the IEEE Third Millennium Medal, and the IEEE EAB Education Award. He also received the Georgia Tech Class of 1934 Distinguished Professor Award in 2004, and was recently named one of the Distinguished Alumni of Pennsylvania State University.

Professor Wong holds over 50 U.S. patents, and has published over 1,000 technical papers.